

MA22D400G

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Reverse voltage $V_R = 60\text{ V}$ is guaranteed
- Small reverse current I_R

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	60	V
Maximum peak reverse voltage	V_{RM}	60	V
Forward current *1	I_F	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	30	A
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: Mounted on an alumina PC board

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Package

- Code
Mini2-F2
- Pin Name
1: Anode
2: Cathode

■ Marking Symbol: 3K



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

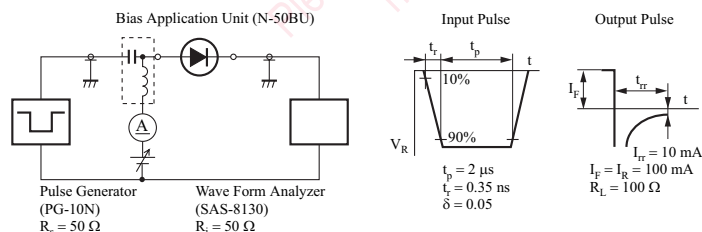
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 1.0\text{ A}$			0.58	V
Reverse current	I_R	$V_R = 60\text{ V}$			30	μA
Terminal capacitance	C_t	$V_R = 0\text{ V}, f = 1\text{ MHz}$		200		pF
Reverse recovery time *1,2	t_{rr}	$I_F = I_R = 100\text{ mA}$ $I_{rr} = 10\text{ mA}, R_L = 100\ \Omega$		13		ns
Thermal resistance (j-a) *1	$R_{th(j-a)}$	Mounted on an alumina PC board		130		$^\circ\text{C/W}$
		Mounted on a glass epoxy PC board *3		200		

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. *1: Design guaranteed

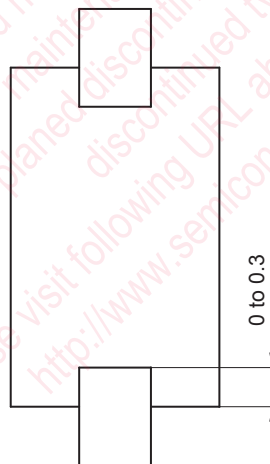
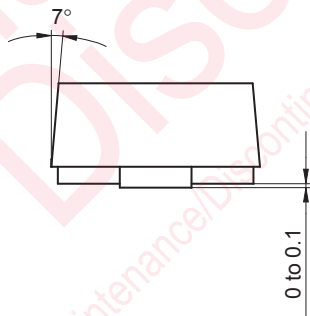
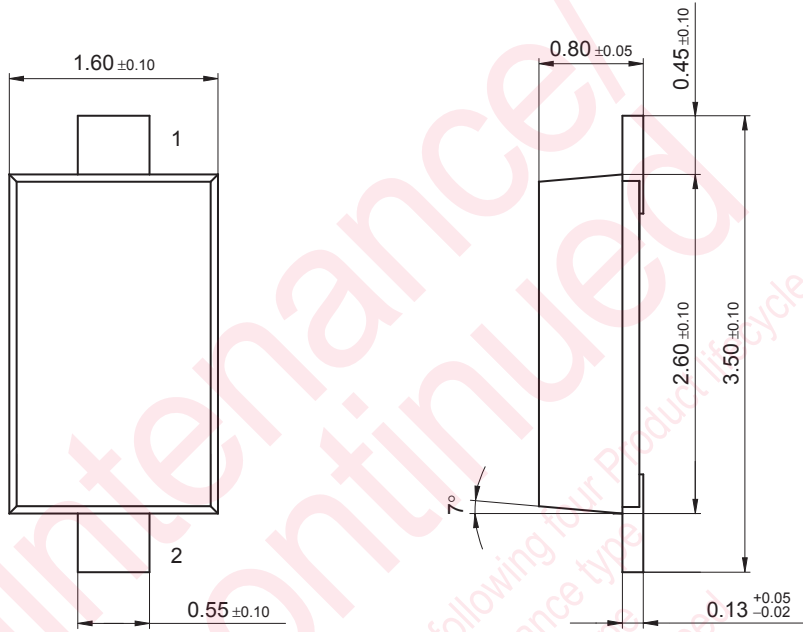
*2: t_{rr} measurement circuit



*3: Mounted on a glass epoxy PC board (Board: 50 mm × 20 mm × 1.0 t, Soldering land: 2.0 mm × 2.0 mm + 0.8 mm × 2.0 mm)

Mini2-F2

Unit: mm



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